#### 3.2x2.8mm SURFACE MOUNT LED LAMP

Part Number: KA-3528SECKT-J3-09 Red

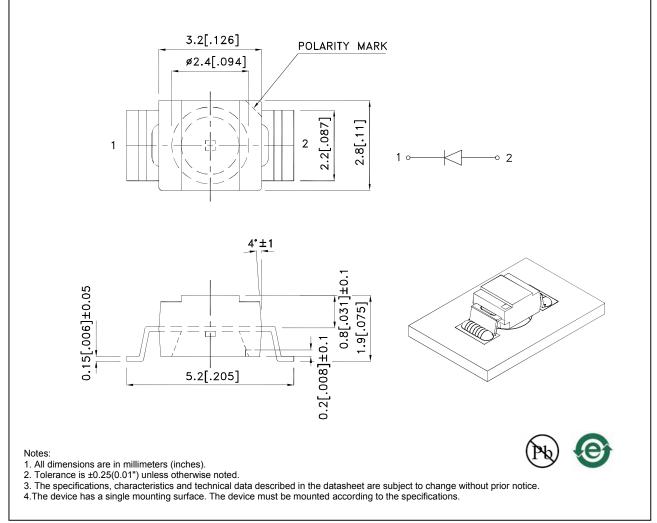
#### **Features**

- Single color.
- Suitable for all SMT assembly and solder process.
- Available on tape and reel.
- Ideal for backlighting.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 4.
- RoHS compliant.

#### Description

The Hyper Red device is based on light emitting diode chip made from AlGaInP.

#### **Package Dimensions**



**REV NO: V.1A CHECKED: Allen Liu** 

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#### Selection Guide

Selection Guide					
Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
KA-3528SECKT-J3-09	Pod (AlColnP)	Water Clear	1000	1500	120°
	Red (AlGaInP)		*300	*450	

Notes:

1.  $\theta$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity/ luminous Flux: +/-15%.

3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

#### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Red	640		nm	IF=20mA
λD [1]	Dominant Wavelength	Red	625		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Red	20		nm	IF=20mA
С	Capacitance	Red	27		pF	VF=0V;f=1MHz
Vf [2]	Forward Voltage	Red	2.2	2.8	V	IF=20mA
lr	Reverse Current	Red		10	uA	VR=5V

Notes:

1.Wavelength: +/-1nm.

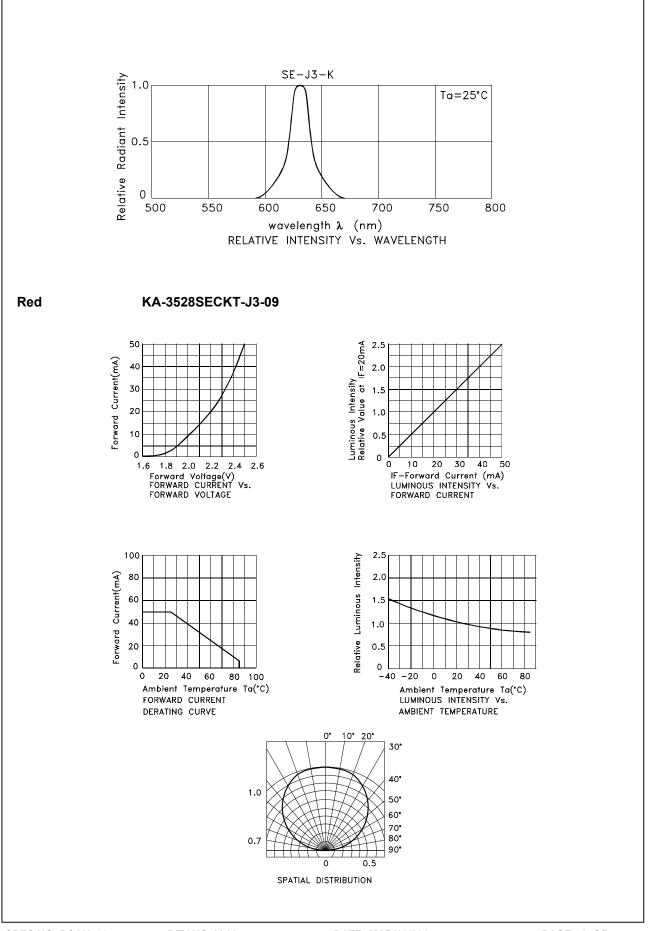
Forward Voltage: +/-0.1V.
Wavelength value is traceable to the CIE127-2007 compliant national standards.

#### Absolute Maximum Ratings at TA=25°C

Parameter	Red	Units		
Power dissipation	140	mW		
DC Forward Current	50	mA		
Peak Forward Current [1]	150	mA		
Reverse Voltage	5	V		
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

Note:

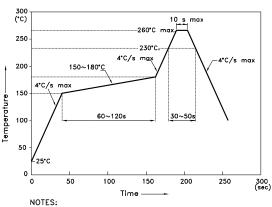
1. 1/10 Duty Cycle, 0.1ms Pulse Width.



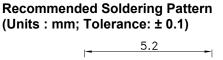
### KA-3528SECKT-J3-09

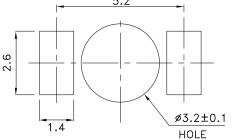
Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

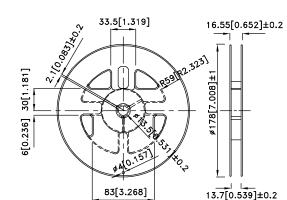
Reflow Soldering Profile For Lead-free SMT Process.



NOTES: 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. 3.Number of reflow process shall be 2 times or less.

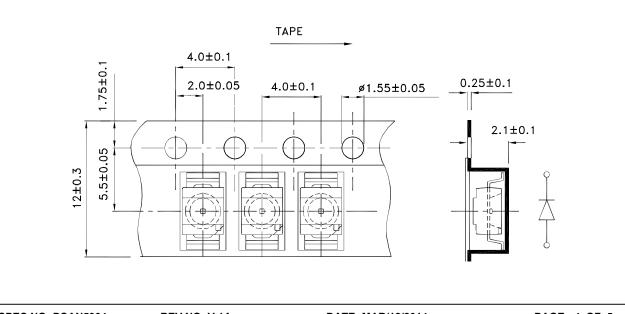




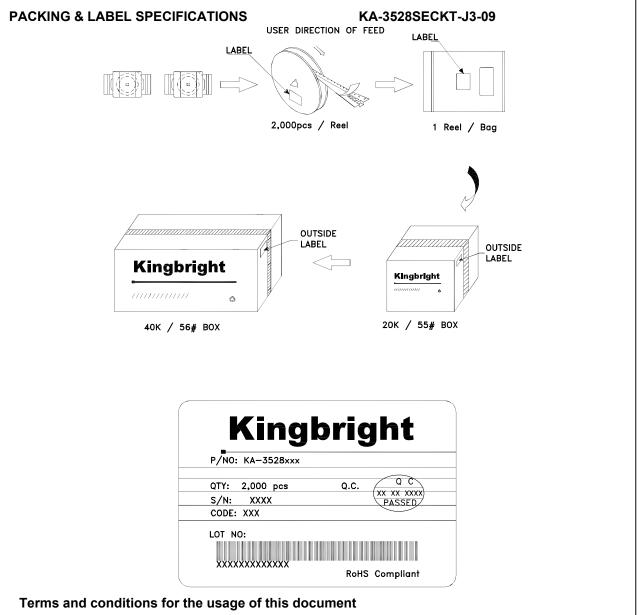


**Reel Dimension** 

#### **Tape Dimensions** (Units : mm)



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- 2. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
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